EXPRESS MAIL No .:

EL 962 858 663 US

Deposited:

**December 22, 2005** 

I hereby certify that this correspondence is being deposited with the United States Postal Service Express mail under 37 CFR-1.10 on the date indicated above and is addressed to: Mail Stop PCT, Commissioner for

Patents, P.O. Box 1450, Alexandria, VA 22313 1450

/ Ruth Montalvo

Date: 12/22/05

**Customer No.** 

026418

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Attorney's Docket No.:

JG-SU-5224/500577.20073

U.S. Application No.:

International Application No.:

PCT/JP2005/006268

International Filing Date:

**MARCH 31, 2005** 

31 MARCH 2005

Priority Date Claimed:

**APRIL 05, 2004** 

04 APRIL 2004

Title of Invention:

MANUFACTURING METHOD OF SEMICONDUCTOR WAFER

AND SEMICONDUCTOR WAFER MANUFACTURED BY THIS

METHOD

Applicant(s) for (DO/EO/US):

Syouji NOGAMI, Yukichi HORIOKA, and Shoichi YAMAUCHI

Mail Stop PCT Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313 1450

## PRELIMINARY AMENDMENT

Sir:

The above-identified application is filed concurrently herewith, please amend the specification as follows:

Amendments to the specification begin on page 2 of this paper.

Amendments to the claims are reflected in the listing of claims, which begin on page 3 of this paper.

Amendments to the Abstract begin on page 8 of this paper.

Remarks / Arguments begin on page 9 of this paper.